#### Effective October 2015 Supersedes April 2013

# **FP3** High current, low profile inductors



#### **Product description**

- · Low profile high current inductors
- Inductance range 0.1µh to 15µh
- Design utilizes high temperature iron powder alloy material with a non-organic binder to eliminate thermal aging
- 7.25 x 6.7mm footprint surface mount package in a 3.0mm height
- Magnetically shielded, low EMI
- Current rating up to 34.7Adc (Higher peak currents may be attained with a greater rolloff, see rolloff curve)
- Frequency range up to 2MHz

#### Applications

- Voltage Regulator Modules (VRMs)
- Multi-phase regulators
- Desktop and server VRMs and EVRDs
- · Notebook and laptop regulators
- Battery power systems
- Graphics cards
- Point-of-load modules

#### **Environmental data**

- Storage temperature range (component): -40°C to +155°C
- Operating temperature range: -40°C to +155°C (ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D





#### **Product specifications**

Part number <sup>6</sup>	OCL (uH) ± 15%	I <sub>rms</sub> <sup>2</sup> amps	I <sub>sat</sub> <sup>3</sup> amps 10%	ا <sub>sat</sub> 4 amps 15%	DCR mOhms @ 20°C typ	DCR mOhms @ 20°C max	K-factor⁵
FP3-R10-R	0.10	19.0	27	34.7	1.00	1.21	803
FP3-R20-R	0.22	15.3	16	20.8	1.54	1.88	482
FP3-R47-R	0.44	10.9	11.6	14.9	3.05	3.67	344
FP3-R68-R	0.72	9.72	9.0	11.6	3.85	4.63	268
FP3-1R0-R	1.10	6.26	7.4	9.5	9.40	11.2	219
FP3-1R5-R	1.50	5.78	6.2	8.0	10.0	13.1	185
FP3-2R0-R	2.00	5.40	5.4	6.9	11.5	15.0	161
FP3-3R3-R	3.20	3.63	4.3	5.5	24.5	30.0	127
FP3-4R7-R	4.70	3.23	3.5	4.2	34.9	40.0	105
FP3-8R2-R	8.5	2.91	2.6	3.4	61.6	74.0	78
FP3-100-R	10.9	2.30	2.3	3.0	84.2	101	69
FP3-150-R	14.9	2.22	2.0	2.5	106.0	127	59

1. OCL (Open Circuit Inductance) Test parameters: 100kHz, 0.1Vrms, 0.0Adc

2.  $I_{_{\rm me}}$  DC current for an approximate  $\Delta T$  of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 155°C under worst case operating conditions verified in the end application.

3.  $\rm I_{sat}$  Amps Peak for approximately 10% rolloff @ 20°C

4. I Amps Peak for approximately 15% rolloff @ 20°C

#### **Dimensions-mm**

5. K-factor: Used to determine Bp-p for core loss (see graph). Bp-p =  $K^*L^*\Delta I$ .

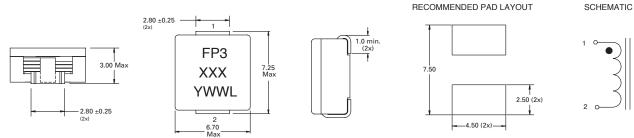
Bpp: (Gauss), K: (K factor from table), L: (Inductance in  $\mu$ H),  $\Delta$ I (Peak to peak ripple current in Amps).

6. Part number definition:

FP3 = product code and size

xxx = inductance value in µH

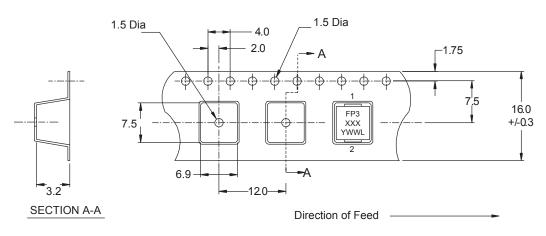
R = decimal point (if no "R" is present, then last character equals the number of zeros) "-R" suffix = RoHS complaint



Part marking: FP3 (Product code and size), xxx=(inductance value in  $\mu$ H), R=decimal point (if no "R" is present, then last character equals the number of zeroes, YWW=Date code, L=Location code

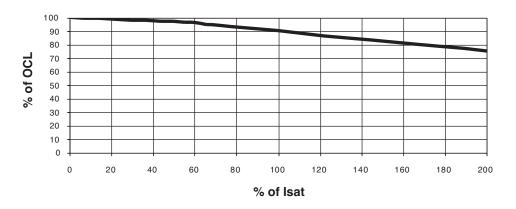
#### Packaging information (mm)

Supplied in tape and reel packaging, 1700 parts per 13" diameter reel

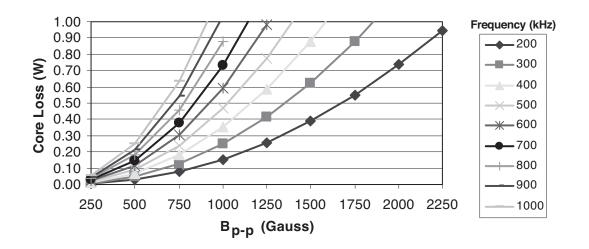


#### Inductance characteristics

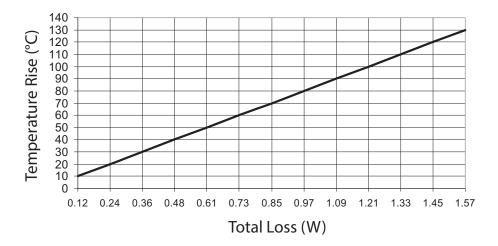
OCL vs. Isat



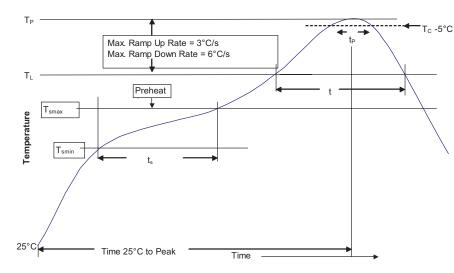
**Core loss** 



Temperature rise vs. total loss



#### Solder reflow profile



### $-_{T_c - 5^{\circ}C}$ Table 1 - Standard SnPb Solder (T<sub>c</sub>)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

#### Table 2 - Lead (Pb) Free Solder (T<sub>c</sub>)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

#### **Reference JDEC J-STD-020D**

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak • Temperature min. (T <sub>smin</sub> )	100°C		
• Temperature max. (T <sub>smax</sub> )	150°C	200°C	
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds	
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>	3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL) Time at liquidous (tL)	183°C 60-150 Seconds	217°C 60-150 Seconds	
Peak package body temperature (Tp)*	Table 1	Table 2	
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature $(T_c)$	20 Seconds**	30 Seconds**	
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.	

\* Tolerance for peak profile temperature (T<sub>n</sub>) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

Eaton Electronics Division 1000 Eaton Boulevard Cleveland, OH 44122 United States www.eaton.com/elx

© 2015 Eaton All Rights Reserved Printed in USA Publication No. 4118 BU-SB13475 October 2015

Eaton is a registered trademark.

All other trademarks are property of their respective owners.



## **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Eaton:

<u>FP3-100-R</u> <u>FP3-R10-R</u> <u>FP3-R20-R</u> <u>FP3-R47-R</u> <u>FP3-R68-R</u> <u>FP3-1R0-R</u> <u>FP3-1R5-R</u> <u>FP3-150-R</u> <u>FP3-2R0-R</u> FP3-3R3-R FP3-4R7-R FP3-8R2-R